

# Designer's™ Data Sheet

## Schottky Power Rectifier

### Surface Mount Power Package

**MBRS1100T3**

Motorola Preferred Device

**SCHOTTKY BARRIER  
RECTIFIER  
1.0 AMPERE  
100 VOLTS**



**CASE 403A-03**

Schottky Power Rectifiers employ the use of the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes, in surface mount applications where compact size and weight are critical to the system. These state-of-the-art devices have the following features:

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- High Blocking Voltage — 100 Volts
- 150°C Operating Junction Temperature
- Guardring for Stress Protection

#### Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 12 mm Tape and Reel, 2500 units per reel
- Polarity: Notch in Plastic Body Indicates Cathode Lead
- Marking: B110

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	100	Volts
Average Rectified Forward Current $T_L = 120^\circ\text{C}$ $T_L = 100^\circ\text{C}$	$I_{F(AV)}$	1.0 2.0	Amps
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	$I_{FSM}$	50	Amps
Operating Junction Temperature	$T_J$	- 65 to +150	°C
Voltage Rate of Change	dv/dt	10	V/ns

#### THERMAL CHARACTERISTICS

Thermal Resistance — Junction to Lead ( $T_L = 25^\circ\text{C}$ )	$R_{\theta JL}$	22	°C/W
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#### ELECTRICAL CHARACTERISTICS

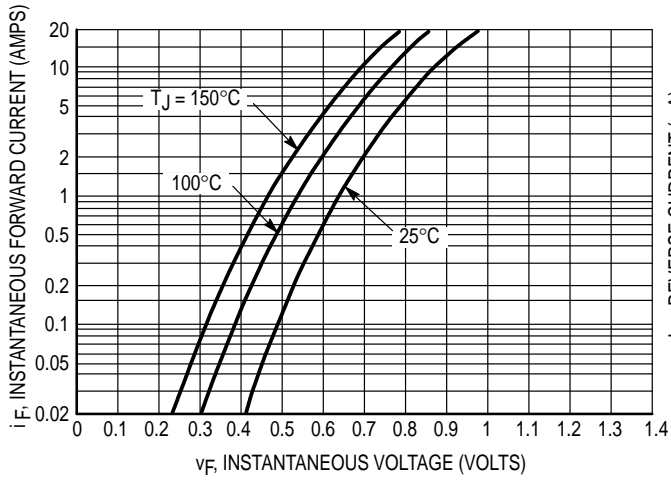
Maximum Instantaneous Forward Voltage (1) ( $i_F = 1.0\text{ A}$ , $T_J = 25^\circ\text{C}$ )	$V_F$	0.75	Volts
Maximum Instantaneous Reverse Current (1) (Rated dc Voltage, $T_J = 25^\circ\text{C}$ ) (Rated dc Voltage, $T_J = 100^\circ\text{C}$ )	$i_R$	0.5 5.0	mA

(1) Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

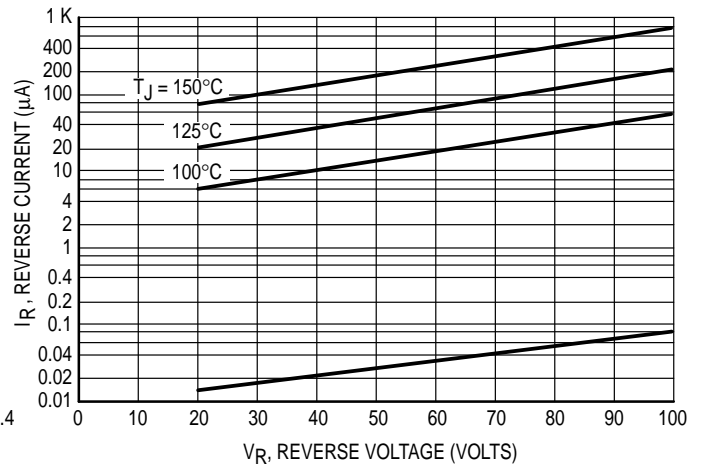
**Preferred** devices are Motorola recommended choices for future use and best overall value.

**Designer's Data for "Worst Case" Conditions** — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.

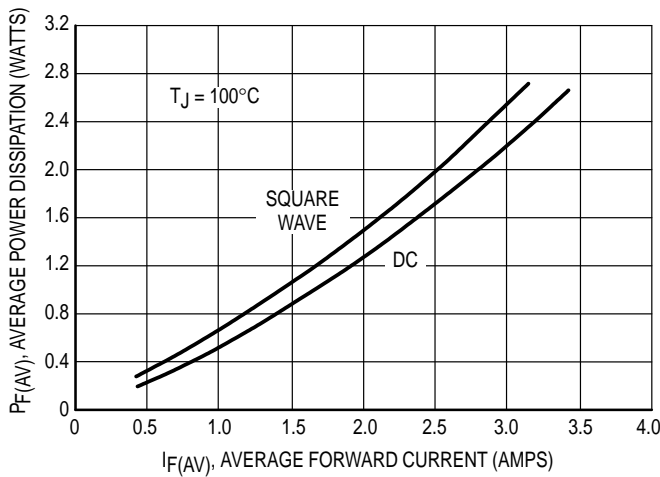
**TYPICAL ELECTRICAL CHARACTERISTICS**



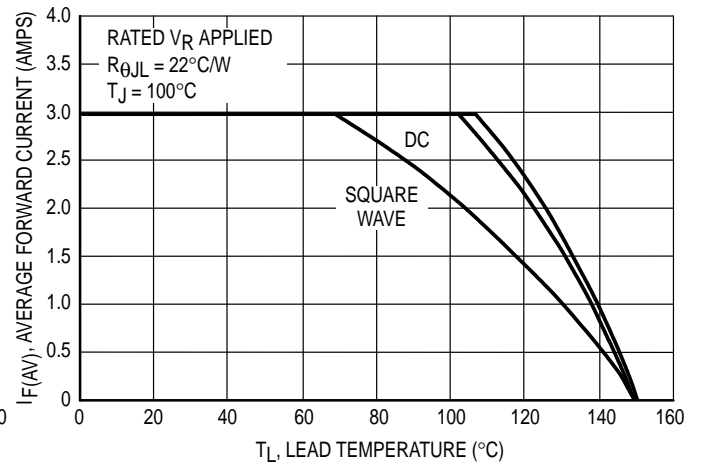
**Figure 1. Typical Forward Voltage**



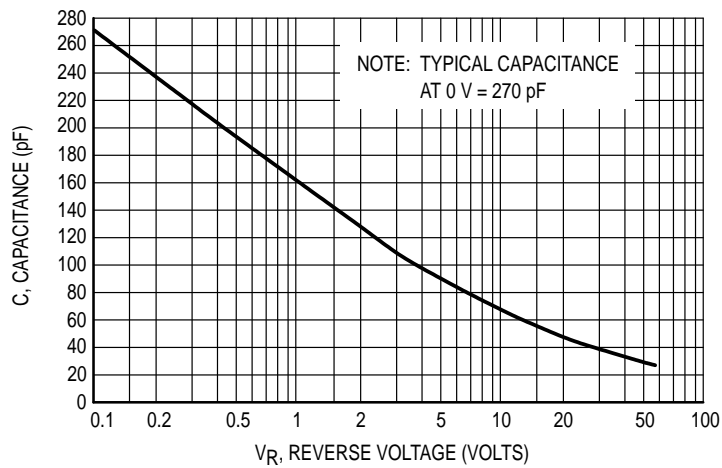
**Figure 2. Typical Reverse Current**



**Figure 3. Power Dissipation**



**Figure 4. Current Derating, Lead**



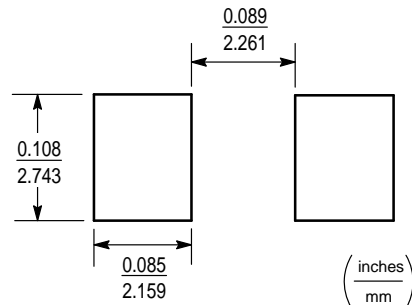
**Figure 5. Typical Capacitance**

## INFORMATION FOR USING THE SMB SURFACE MOUNT PACKAGE

### MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection interface

between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



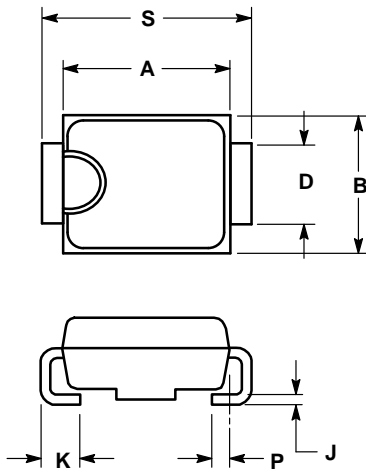
### MOUNTING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.\*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 5 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling

\* Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.


**PACKAGE DIMENSIONS**



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.160	0.180	4.06	4.57
B	0.130	0.150	3.30	3.81
C	0.075	0.095	1.90	2.41
D	0.077	0.083	1.96	2.11
H	0.0020	0.0060	0.051	0.152
J	0.006	0.012	0.15	0.30
K	0.030	0.050	0.76	1.27
P	0.020	REF	0.51	REF
S	0.205	0.220	5.21	5.59

**CASE 403A-03  
ISSUE B**

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